

/ Descriptions

TO-220AC
Ultrafast Recovery Diode in a TO-220AC Plastic Package.

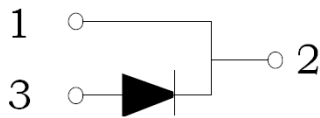
/ Features

Silicon epitaxial process to produce ultrafast recovery diode with low reverse leakage current and high reliability.

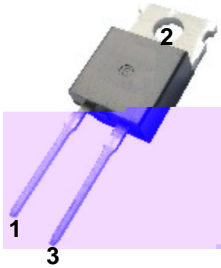
/ Applications

For high frequency, high voltage, high current rectifier diode, freewheeling diode.

/ Equivalent Circuit



/ Pinning



PIN1 2 Cathode

PIN 3 Anode

/ h_{FE} Classifications & Marking

See Marking Instructions

/ Absolute Maximum Ratings(Ta=25)

Parameter	Symbol	Rating	Unit
Peak Repetitive Reverse Voltage	V_{RRM}	600	V
RMS Voltage	V_{RMS}	420	V
DC Blocking Voltage	V_{DC}	600	V
Average Forward Current	I_F	1× 20	A
Peak forward surge current	I_{FSM}	250	A
Typical Thermal Resistance Junction to Case	R_{Jc}	2.8	/W
Junction Temperature Range	T_j	150	
Storage Temperature Range	T_{stg}	-55 150	

/ Electrical Characteristics(Ta=25)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Forward Voltage	V_F	$I_F=5.0A$ $T_C=25$			1.35	V
		$I_F=5.0A$ $T_C=150$			1.15	
		$I_F=20A$ $T_C=25$			1.65	
		$I_F=20A$ $T_C=150$			1.25	
Instantaneous Reverse Current(Note1)	I_R	$V_R=600V$ $T_a=25$			0.25	mA
		$V_R=420V$ $T_a=150$			1.0	
		$V_R=600V$ $T_a=150$			2.0	
Reverse Recovery Time	t_{rr}	$I_F=0.5A$ $I_{RR}=0.25A$ $I_R=1.0A$			50	ns

/Notes

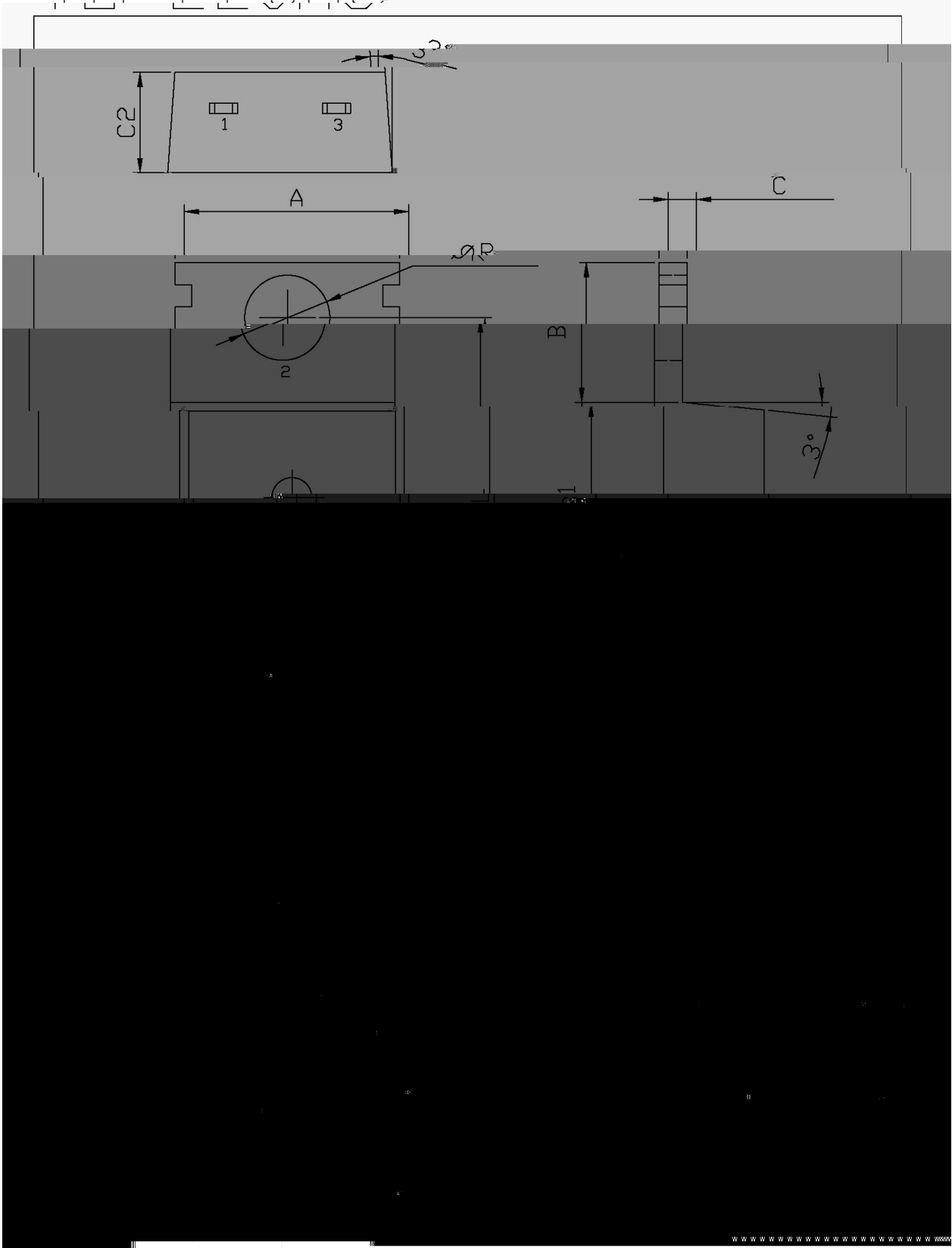
1. /Short duration pulse test used to minimize self-heating effect.
2. / Unless otherwise noted, values for the parameters of a single chip

MUR2060

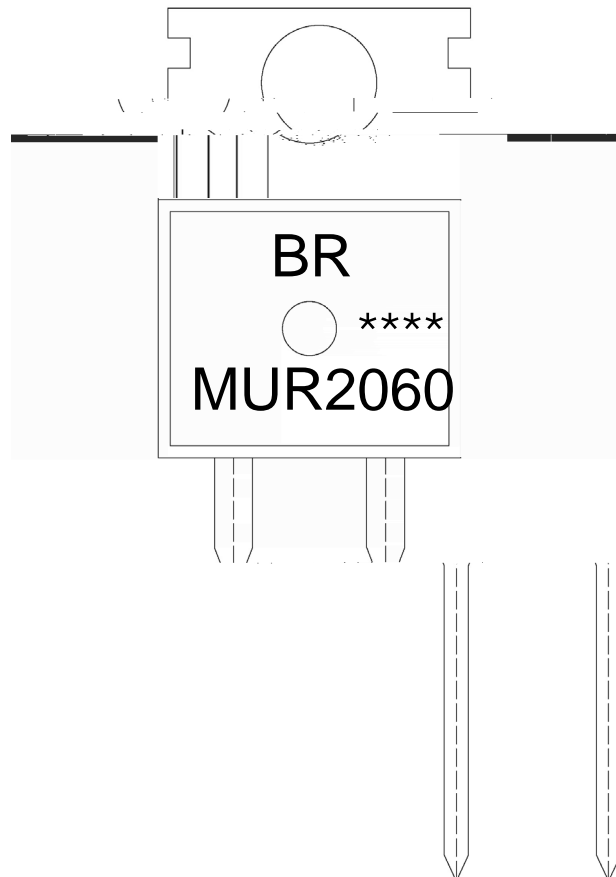
/ Package Dimensions

TO-220AC

Unit:mm



/ Marking Instructions



BR

MUR2060

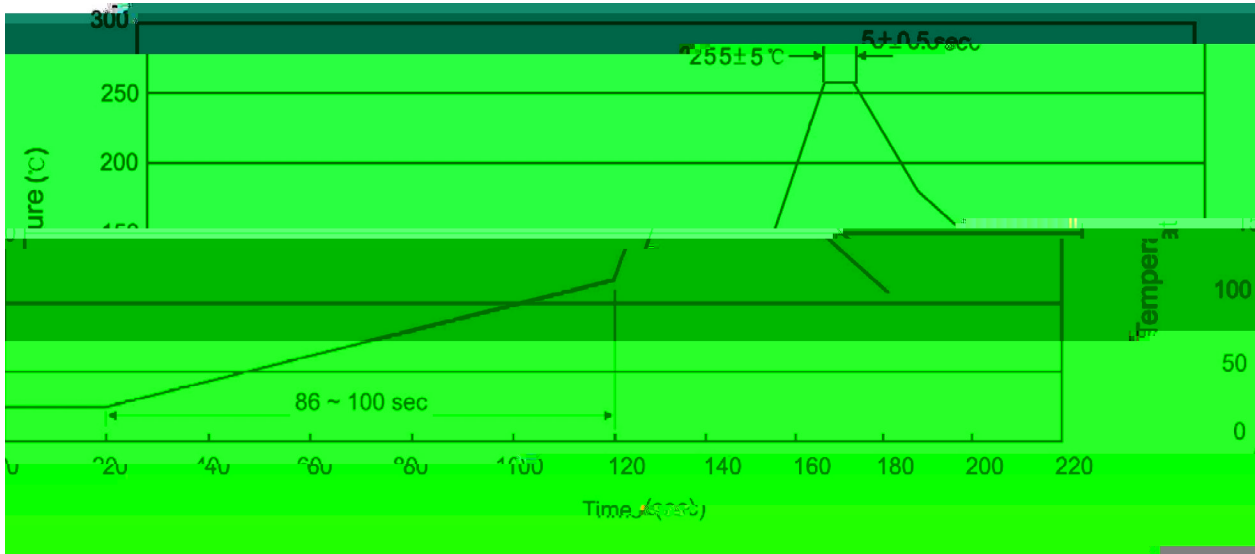
Note:

BR: Company Code

MUR2060 Product Type.

****: Lot No. Code, code change with Lot No.

() / Temperature Profile for Dip Soldering(Pb-Free)



- | | | | | | | |
|---|-------|-----|-----------|--------|---|--------------------------------------|
| 1 | 25 | 150 | 60 | 90sec; | Note: | 1.Preheating:25~150 , Time:60~90sec. |
| 2 | 255±5 | | 5±0.5sec; | | 2.Peak Temp.:255±5 , Duration:5±0.5sec. | |
| 3 | | 2 | 10 | /sec. | 3. Cooling Speed: 2~10 /sec. | |

/ Resistance to Soldering Heat Test Conditions

270±5 10±1 sec. Temp.:270±5 Time:10±1 sec

/ Packaging SPEC.

/ BULK

Package Type 封装形式	Units/Bag 只/袋	Bags/Inner Box 袋/盒	Units 包装数量 Units/Inner Box 只/盒	Dimension 包装尺寸 (unit: mm ³)
----------------------	------------------	-----------------------	--------------------------------------	---